

in Silicone resin

Solvent based coatings

Evonik Tego formulation No. 17455

Rev. Number: 01.01

03/17

Function	Product	Producer	PBW
Methyl phenyl silicone resin	SILIKOPHEN® P80/X	Evonik	42.50
Wetting and dispersing agent	TEGO® Dispers 670	Evonik	1.00
Rheology modifier	BENTONE® 38	Elementis	0.30
Solvent	Isobutyl alcohol		0.50
Solvent	Butyl glycol acetate		1.20
Defoamer/Deaerator	TEGO® Airex 900	Evonik	0.50
Muscovite mica	MICA TM	Aspanger	17.80
Anticorrosive pigment	HEUCOPHOS® ZPA	Sudarshan	4.90
Copper chromite black spinel	HEUCODUR® Black 9-100	Sudarshan	6.30
Rheology modifier	AEROSIL® 200	Evonik	0.50
Grind with a bead mill.			
Solvent	Xylene		24.50
Add while stirring.			

100.00

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